AIM 35.7Sn/35.7Pb/28.6Bi Solder for Photonic Packaging

Category : Metal , Nonferrous Metal , Lead Alloy , Solder/Braze Alloy , Tin Alloy

Material Notes:

Uses include:Fiber to Ferrule SolderingLaser Die AttachHermetic Packaging & SealingWetting & Sealing Laser OpticsThermal ManagementInformation provided by AIM Specialty Materials.

Order this product through the following link:
http://www.lookpolymers.com/polymer_AIM-357Sn357Pb286Bi-Solder-for-Photonic-Packaging.php

Physical Properties	Metric	English	Comments
Density	9.34 g/cc	0.337 lb/in³	

Mechanical Properties	Metric	English	Comments
Tensile Strength, Ultimate	165 MPa	24000 psi	

Thermal Properties	Metric	English	Comments
CTE, linear	20.0 µm/m-°C @Temperature 20.0 °C	11.1 µin/in-°F @Temperature 68.0 °F	
Melting Point	100 °C	212 °F	
Solidus	100 °C	212 °F	
Liquidus	100 °C	212 °F	

Component Elements Properties	Metric	English	Comments
Bismuth, Bi	28.6 %	28.6 %	
Lead, Pb	35.7 %	35.7 %	
Tin, Sn	35.7 %	35.7 %	

Descriptive Properties	Value	Comments
Creep Resistance	Low	

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